

## **System in Package and Failure Analysis Challenges**

Miniaturization in the Semiconductors activities has lead to the use of more and more System in Package solutions in final products for domestic electronic and portable appliances. After a brief overview of the overall SiP technologies and some product applications I will describe practical problem we are facing today on our products related to new packaging and processes. Then I will discuss the failure analysis methodology and tools that can be used to solve some of the issues before to conclude with chalenges for coming years.